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HKUST Mechanical Engineers Honored

Prof Tongxi Yu and Dr Ricky Lee of the Hong Kong University of Science and Technology (HKUST) have been elected 2003 Fellows of the American Society of Mechanical Engineers (ASME) in recognition of their significant engineering achievements.

Dr Reginald I Vachon, ASME President, visited HKUST today (30 March) and presented Fellowship Certificates to Prof Yu, Head of the Department of Mechanical Engineering, and his colleague, Associate Professor Dr Lee. Founded in 1880, ASME is a leading professional organization that has a worldwide membership of 125,000. Only 2% of its members are elected Fellows.

The honors highlight the contributions the Department has made towards the advancement of knowledge and research relevant to the economic development of Hong Kong. In the last few years its research efforts, conducted in collaboration with the industrial and business sectors, have concentrated on the development of energy and thermal systems, electronic packaging, micro-electrical-mechanical systems, advanced materials and precision engineering.

A study based on the Science Citation Index (SCI) finds that the Department ranked among the top three in the world from 2000 to 2003 in terms of the number of academic papers published in SCI journals per faculty member per year. This places HKUST alongside other universities such as Princeton, Stanford, Caltech and the University of Illinois at Urbana-Champaign.

"Our vision is to provide quality education and emerge as one of the world's leading mechanical engineering departments. It is a heartening testament to our efforts when any of our faculty receive honors," says Prof Yu.

ASME President Dr Vachon (right) presents certificates to Prof Yu (top) and Dr Lee (bottom)

Prof Yu is an expert in impact dynamics, engineering plasticity and the energy absorption of materials. He has published more than 240 journal papers, co-authored eight books, and sits on the editorial boards of nine prestigious academic journals. His list of accolades includes: an ScD from Cambridge University, 1995; the China Higher Education Science and Technology Award (first class), 2001; and the IFAI Expo 2002 Technical Fabrics Excellence Award. He was also recently elected a Fellow of the prestigious, UK-based, Institute of Mechanical Engineers.

Since 2002, Prof Yu has served as Director of the Institute of Integrated Microsystems at HKUST. He is active in providing consultancy services to industry relating to engineering failure analysis and traffic accident reconstruction.

Prof Yu graduated from Peking University in 1964, and received his PhD from Cambridge University in 1983. From 1984 to 1991, he was a professor in the Department of Mechanics at Peking University. Prior to joining HKUST in 1995, he was Reader in the Department of Mechanical Engineering at the University of Manchester Institute of Science and Technology, UK.

Dr Ricky Lee is an expert in electronic packaging, flip chip and surface mount technologies. As Director of the HKUST Electronic Packaging Laboratory (EPACK Lab), he specializes in failure analyses of integrated circuit (IC) packages and reliability studies of electronic interconnects. He has published more than 100 technical papers, co-authored three books, and has twice won the JEP Best Paper Award (2000 and 2001), conferred by *ASME Transactions: Journal of Electronic Packaging* . He also sits on the editorial boards of four international journals.

Dr Lee is extremely active in professional service. He was Vice-Chair of ASME International's Hong Kong Section (1997-1998) , and Chair of the Components, Packaging & Manufacturing Technology Society, Hong Kong Chapter (2001to 2003). He received his PhD in Aeronautical and Astronautical Engineering from Purdue University in 1992, and joined HKUST in 1993.